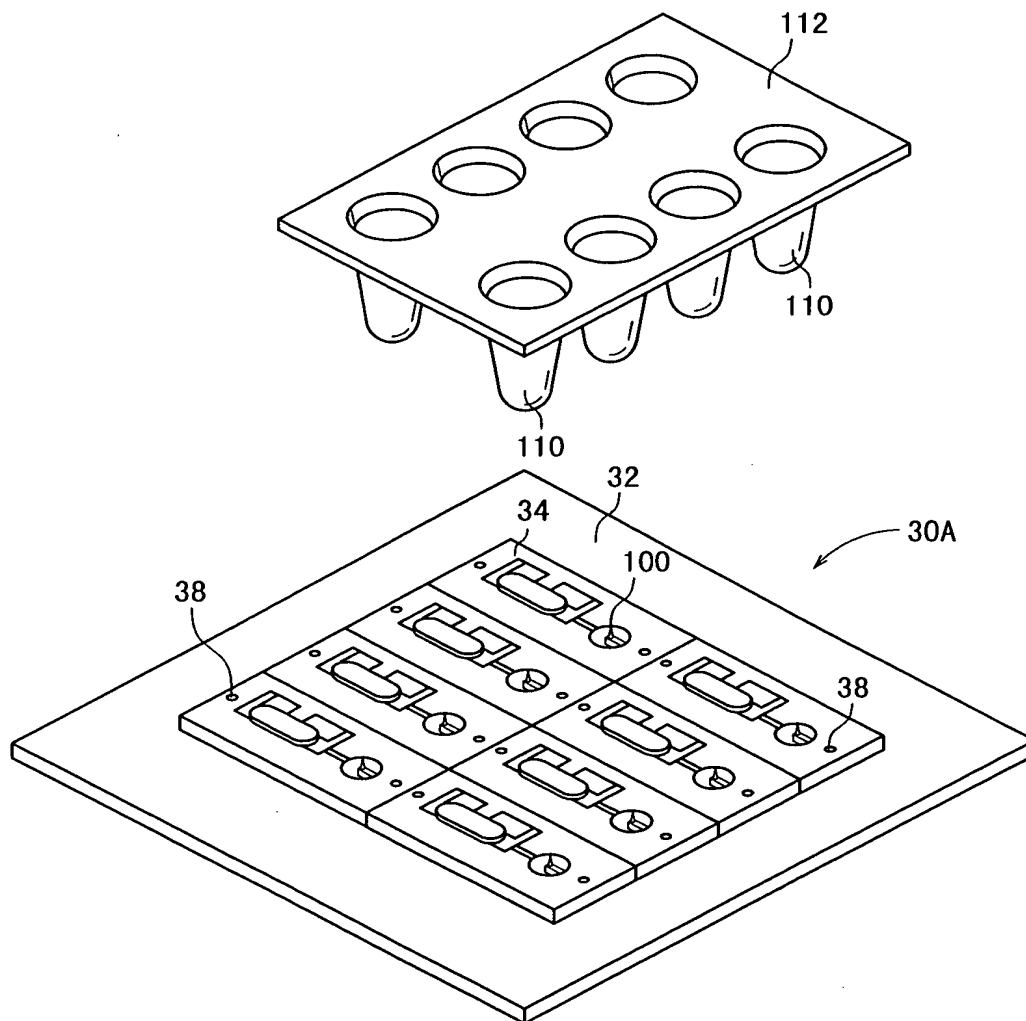


APPROVED	O.G. FIG.	
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FIG. 1

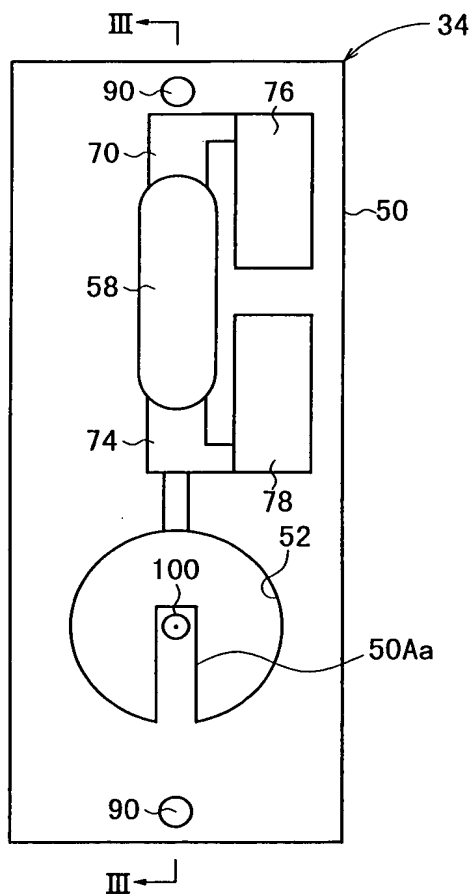


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 Our Docket No.: 789_060

2/22

FIG. 2

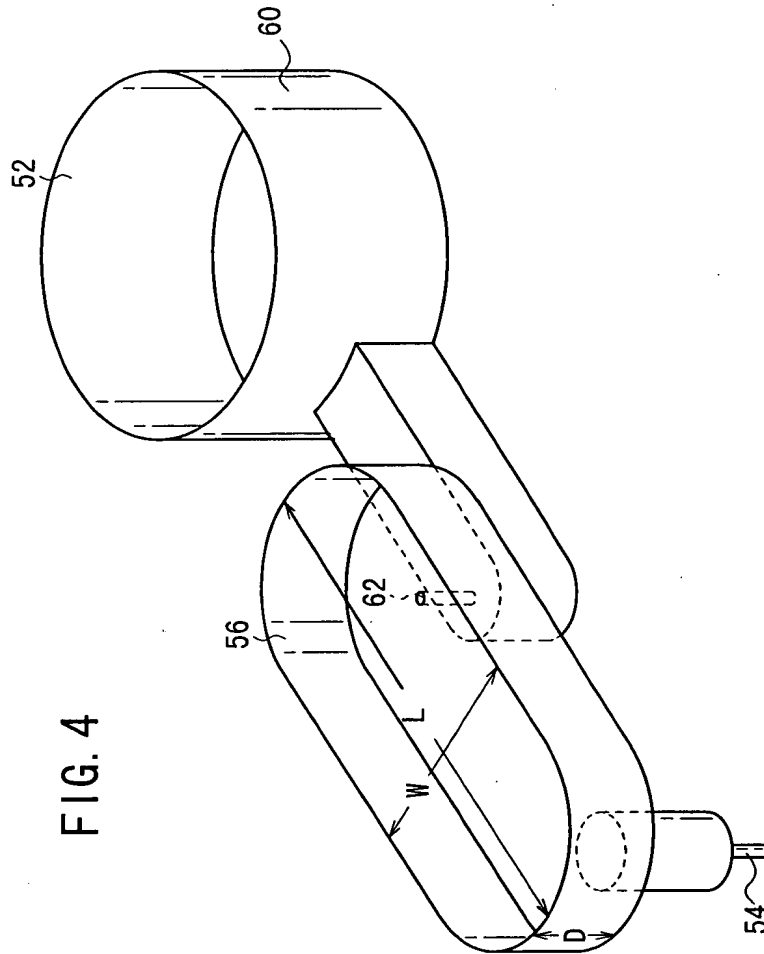


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4/22

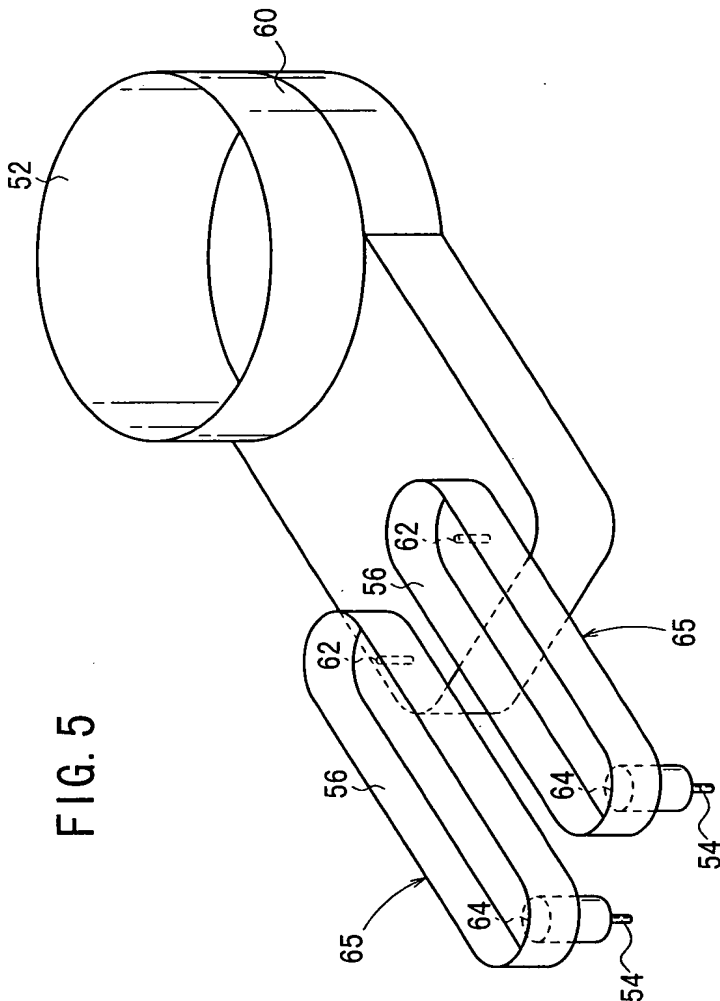
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5/22

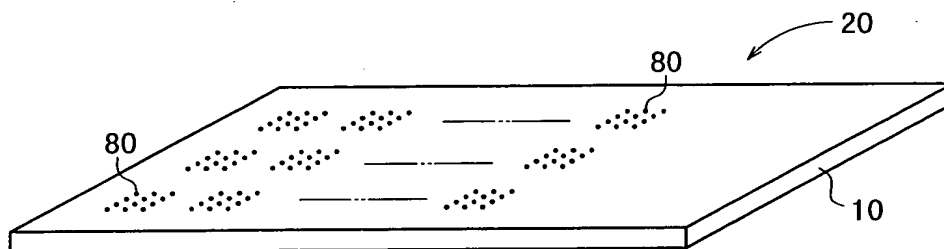


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6/22

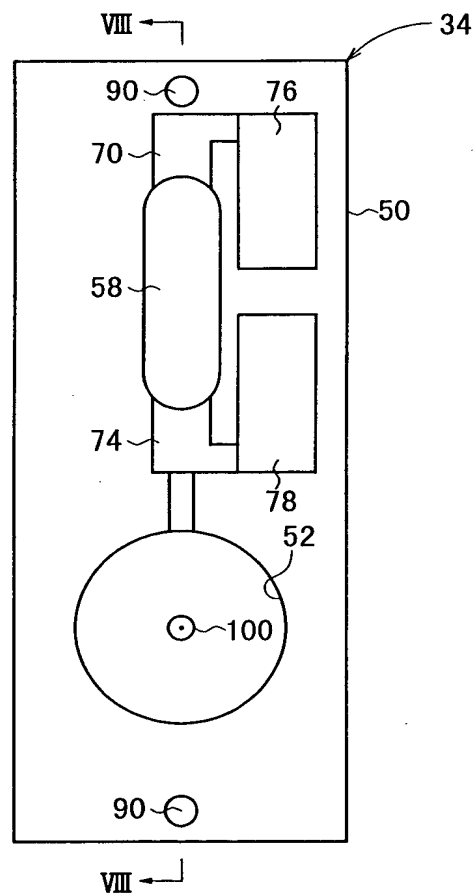
FIG. 6



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FIG. 7



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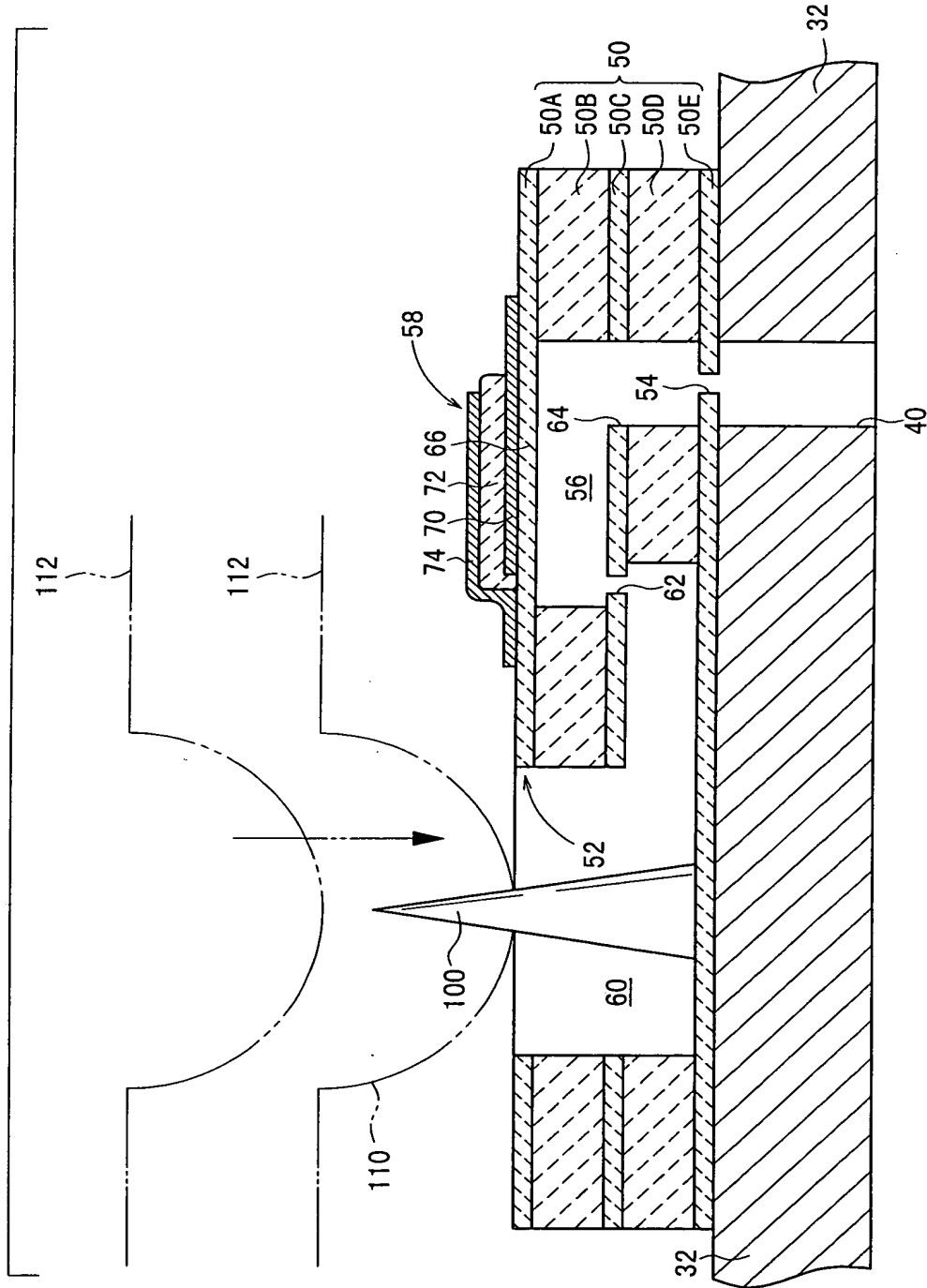
APPROVED	O.G. FIG.	
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 Our Docket No.: 789_060

8/22

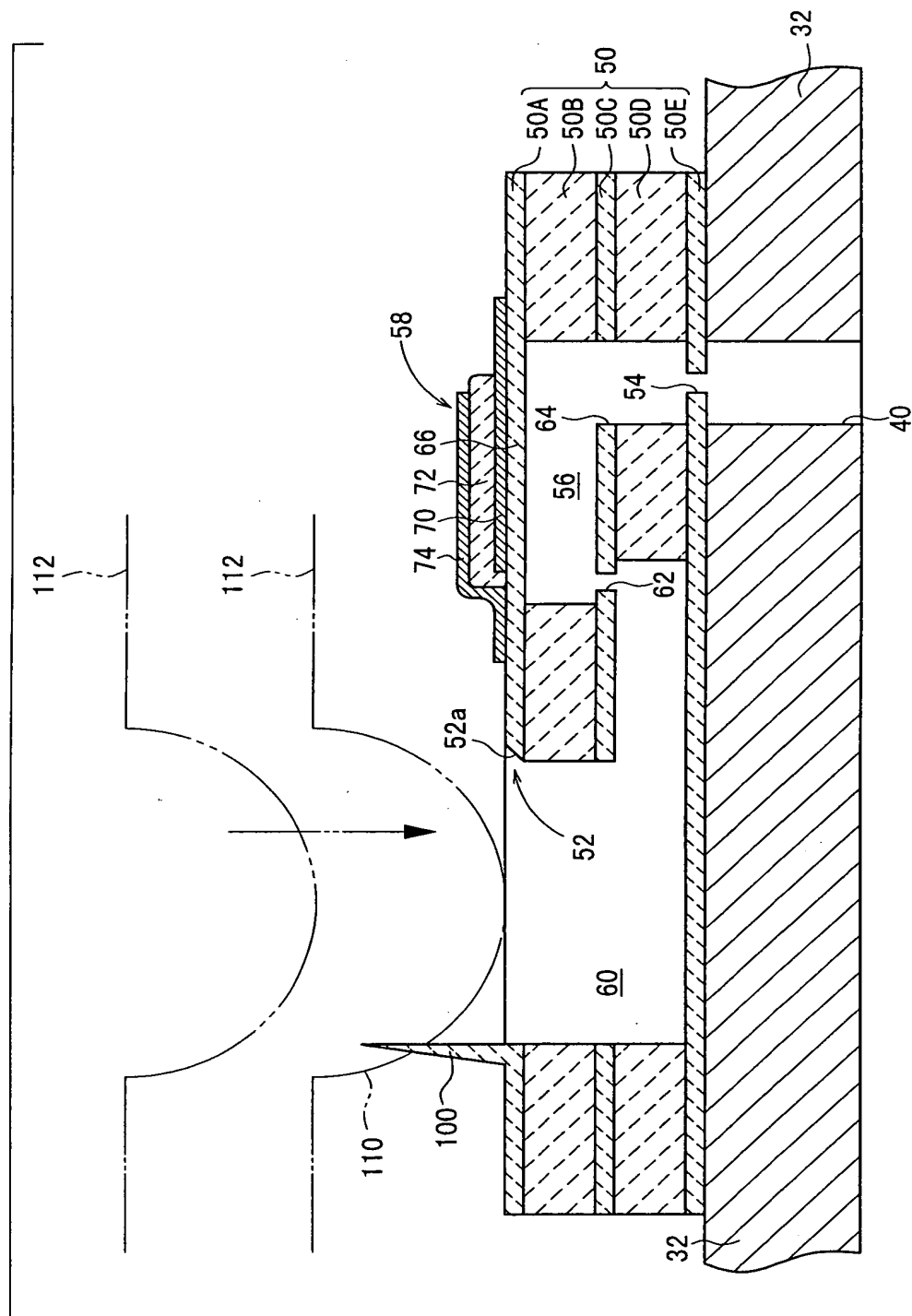
000007 000000

FIG. 8



[illegible]

FIG. 9

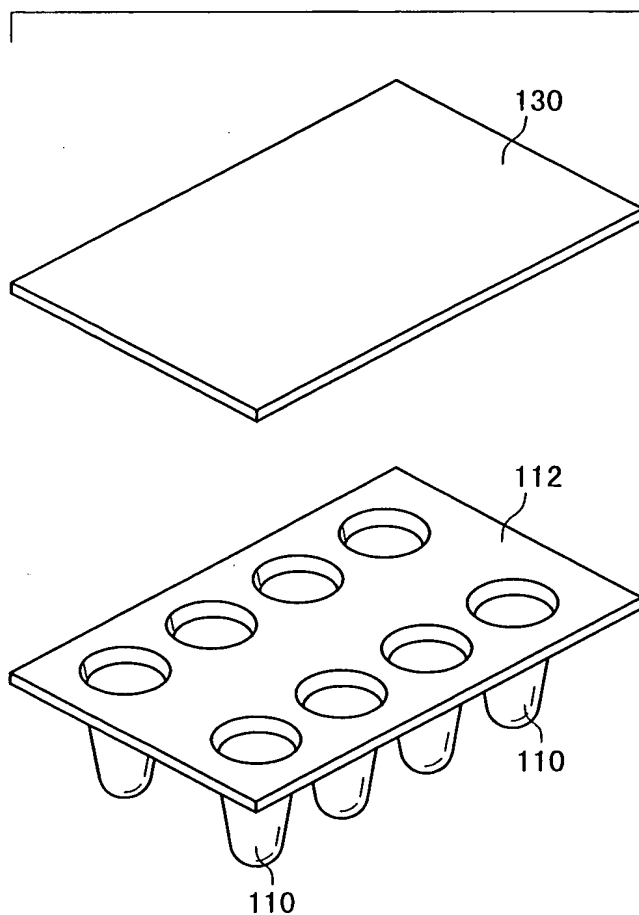


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Our Docket No.: 789_060

10/22

FIG. 10



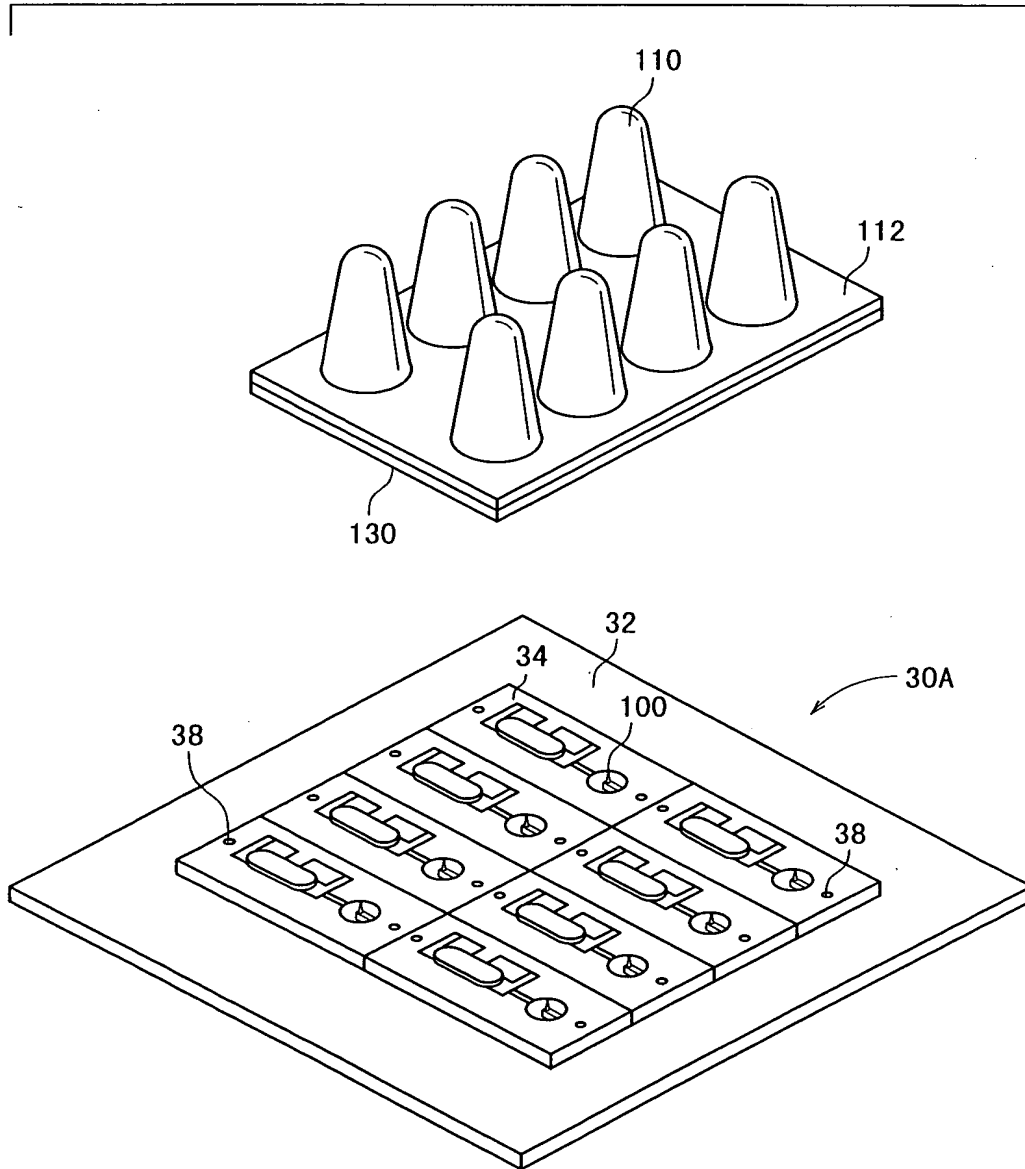
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 Our Docket No.: 789_060

11/22

FIG. 11



Docket 789_060

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FIG. 12

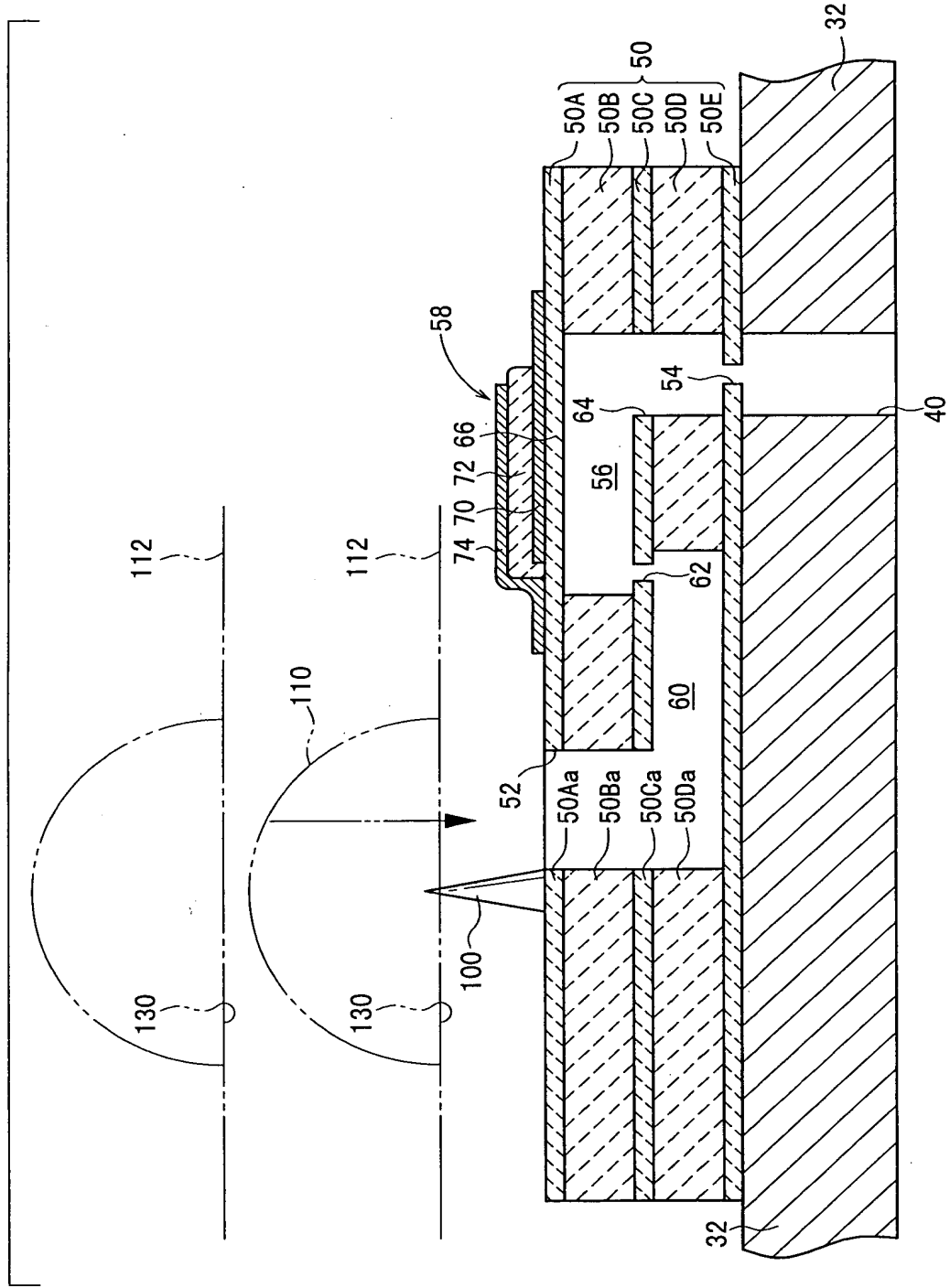


FIG. 13A

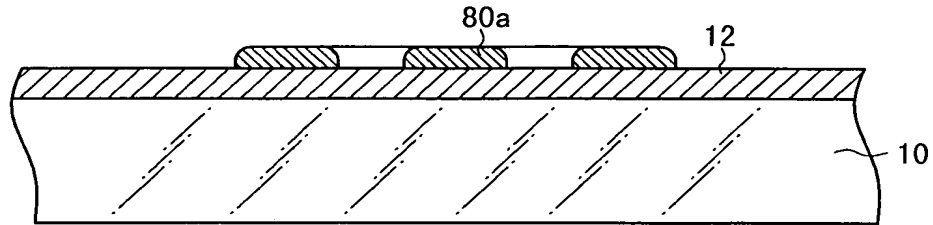
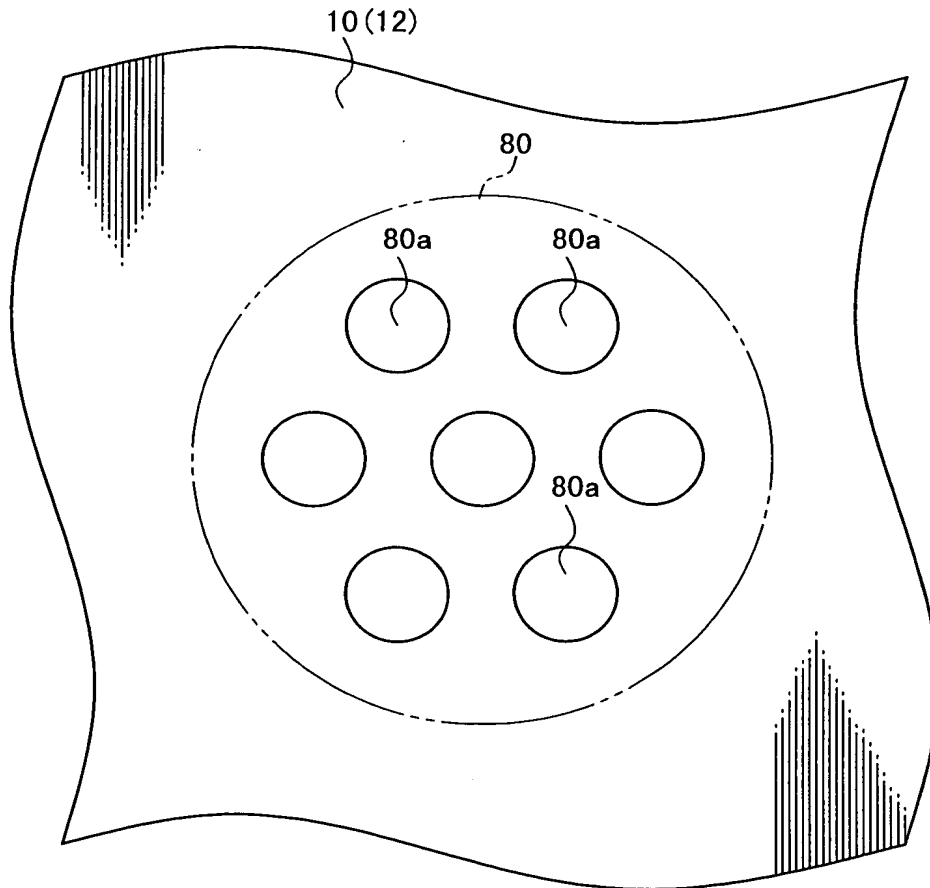


FIG. 13B



14/22

FIG. 14A

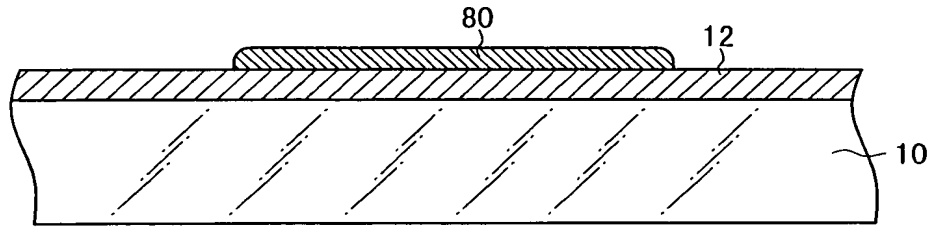
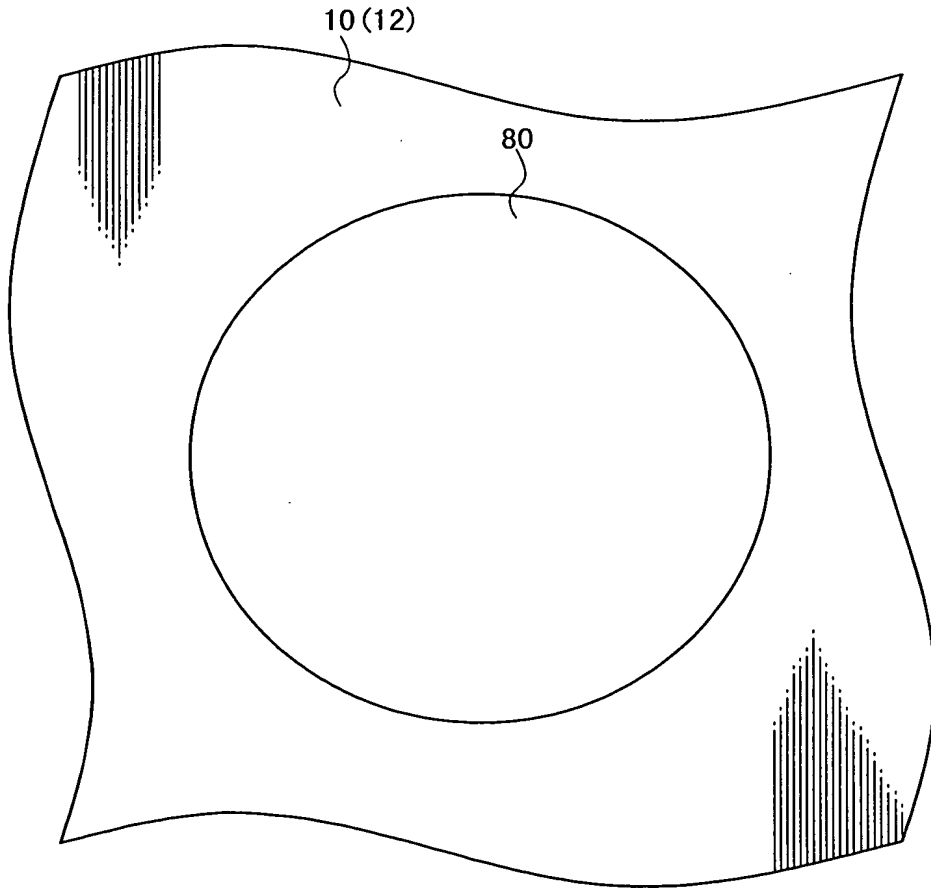


FIG. 14B



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FIG. 16A is a perspective view of a multi-lane assay plate assembly. The assembly includes a horizontal bar 144 supported by vertical pins 142. Below the bar, four assay plates 34 are arranged in a row. Each plate 34 has a central well 140 and a series of smaller wells 52. A pen 30B is shown pointing to the rightmost plate 34.

FIG. 16B is a perspective view of a substrate assembly 10. The assembly includes a substrate 10 and four modules 30B. Each module 30B consists of a base 34, a component 52, and a component 140. The modules are arranged in a row on the substrate 10, with a gap 80 between them.

FIG. 17A

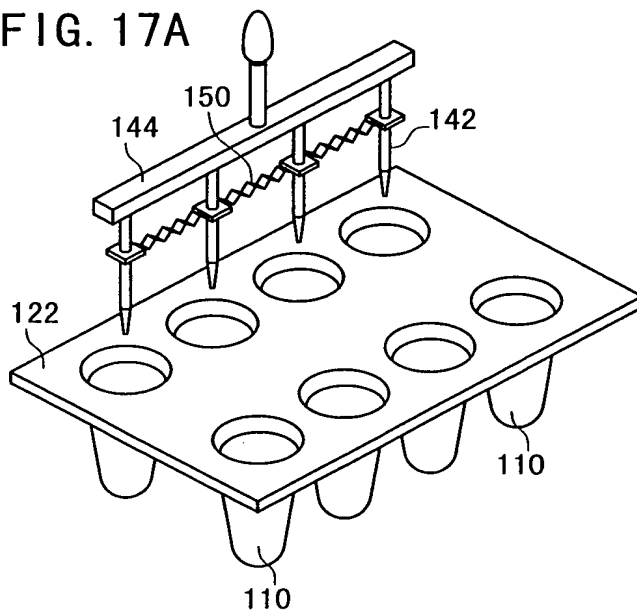


FIG. 17B

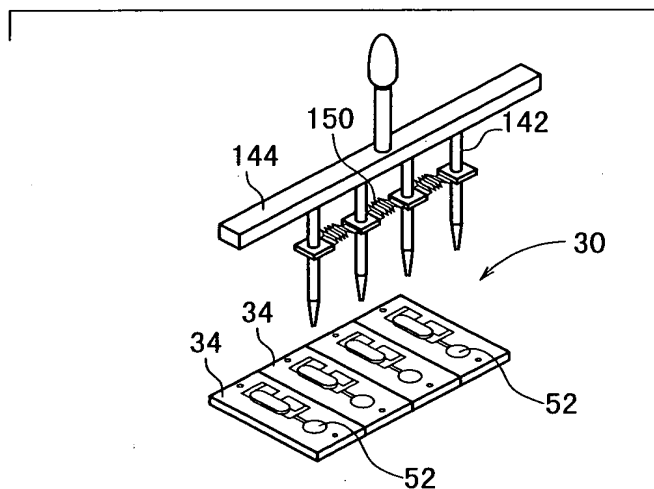
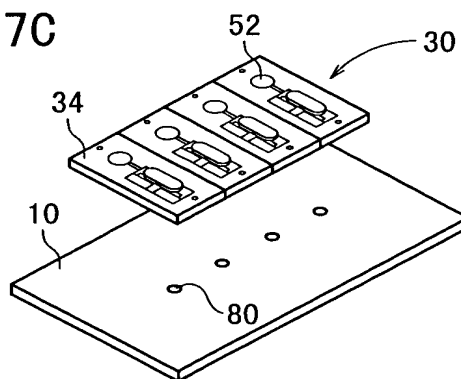


FIG. 17C

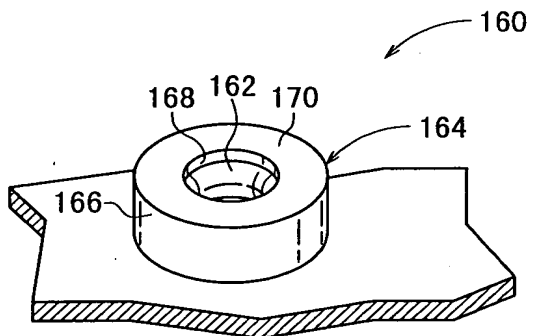


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19/22

FIG. 19

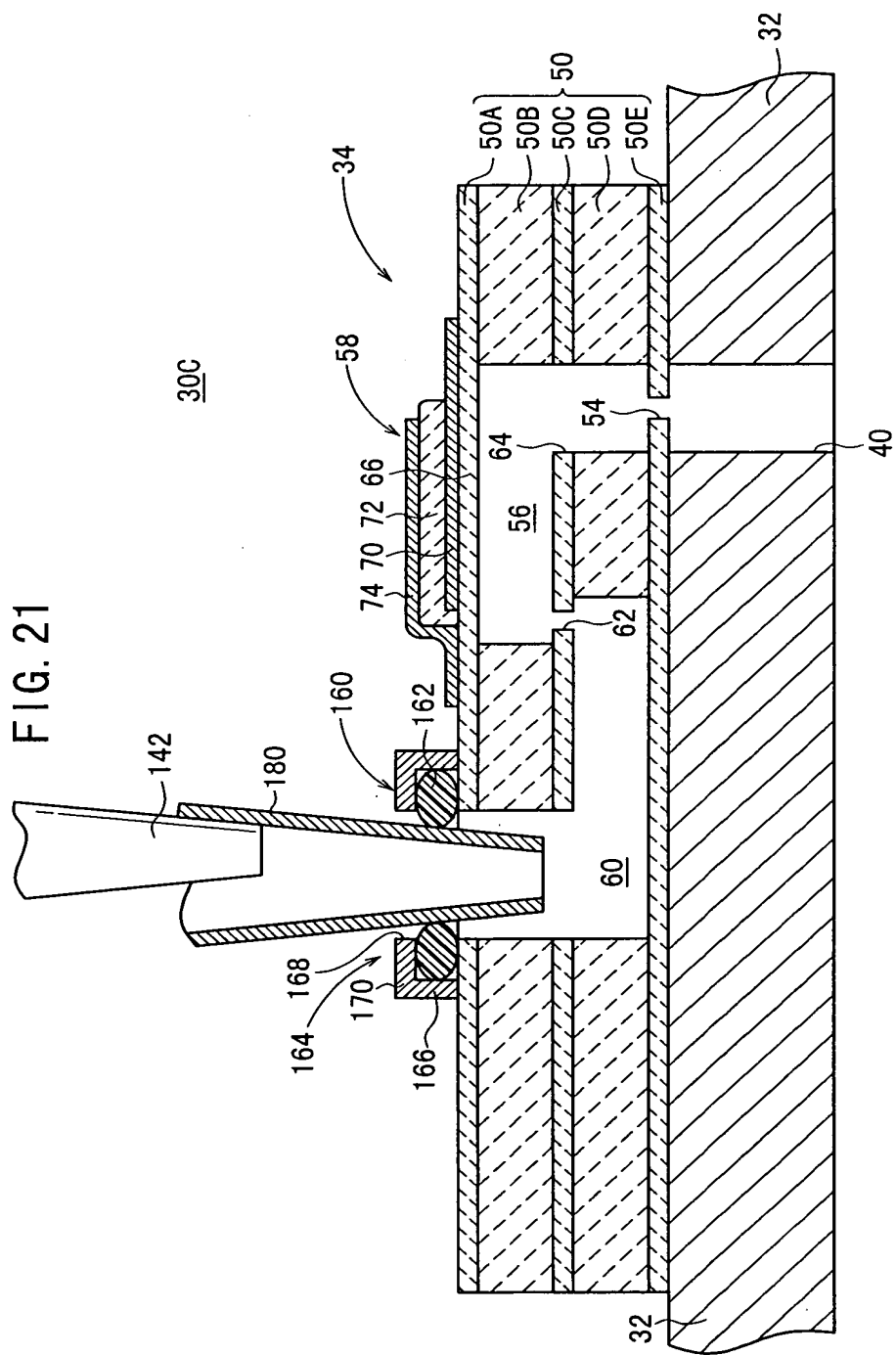


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21/22



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